

<b>PCN Number:</b>	20240502001.1		<b>PCN Date:</b>	May 02, 2024																			
<b>Title:</b>	Qualification of RFAB as an additional Fab site and Die Revision option for select devices																						
<b>Customer Contact:</b>	Change Management Team		<b>Dept:</b>	Quality Services																			
<b>Proposed 1<sup>st</sup> Ship Date:</b>	July 31, 2024		<b>Sample requests accepted until:</b>	June 01, 2024*																			
*Sample requests received after June 01, 2024 will not be supported.																							
<b>Change Type:</b>																							
<input type="checkbox"/>	Assembly Site	<input checked="" type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material																		
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process																		
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input checked="" type="checkbox"/>	Wafer Fab Site																		
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input checked="" type="checkbox"/>	Wafer Fab Material																		
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input checked="" type="checkbox"/>	Wafer Fab Process																		
<b>PCN Details</b>																							
<b>Description of Change:</b>																							
Texas Instruments is pleased to announce the qualification of its RFAB fabrication facility as an additional Wafer Fab option for the devices listed below.																							
<table border="1"> <thead> <tr> <th colspan="3">Current Fab Site</th> <th colspan="3">Additional Fab site</th> </tr> <tr> <th>Current Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> <th>Additional Fab site</th> <th>Process</th> <th>Wafer Diameter</th> </tr> </thead> <tbody> <tr> <td>MIHO8</td> <td>LBC8</td> <td>200mm</td> <td>RFAB</td> <td>LBC9</td> <td>300mm</td> </tr> </tbody> </table>						Current Fab Site			Additional Fab site			Current Fab Site	Process	Wafer Diameter	Additional Fab site	Process	Wafer Diameter	MIHO8	LBC8	200mm	RFAB	LBC9	300mm
Current Fab Site			Additional Fab site																				
Current Fab Site	Process	Wafer Diameter	Additional Fab site	Process	Wafer Diameter																		
MIHO8	LBC8	200mm	RFAB	LBC9	300mm																		
The die was also changed as a result of the process change.																							
<b>Reason for Change:</b>																							
Supply Continuity																							
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>																							
None																							
<b>Impact on Environmental Ratings</b>																							
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.																							
<b>RoHS</b>		<b>REACH</b>		<b>Green Status</b>																			
<input checked="" type="checkbox"/> No Change		<input checked="" type="checkbox"/> No Change		<input checked="" type="checkbox"/> No Change																			
<b>IEC 62474</b>																							
<input checked="" type="checkbox"/> No Change																							
<b>Changes to product identification resulting from this PCN:</b>																							
<b>Fab Site Information:</b>																							
Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City																				
MIHO8	MH8	JPN	Ibaraki																				
<b>RFAB</b>	<b>RFB</b>	<b>USA</b>	<b>Richardson</b>																				
<b>Die Rev:</b>																							
<b>Current</b>		<b>New</b>																					
Die Rev [2P]		Die Rev [2P]																					
A		C																					

Sample product shipping label (not actual product label):



MADE IN: Malaysia  
2DC: 2Q:

MSL 2 / 260C/1 YEAR	SEAL DT
MSL 1 / 235C/UNLIM	03/29/04

OPT:  
ITEM: 39  
LBL: 5A (L)T0:1750





(1P) SN74LS07NSR  
(Q) 2000 (D) 0336  
(31T) LOT: 3959047MLA  
(4W) TKY (1T) 7523483SI2  
(P)  
(2P) REV: (V) 0033317  
(20L) CS0: SHE (21L) CCO:USA  
(22L) AS0: MLA (23L) ACO: MYS

**Product Affected:**

DRV5055Z1QDBZR	DRV5056A1QDBZR	DRV5056A6QDBZR	DRV5056Z4QDBZR
DRV5055Z2QDBZR	DRV5056A2QDBZR	DRV5056Z1QDBZR	
DRV5055Z3QDBZR	DRV5056A3QDBZR	DRV5056Z2QDBZR	
DRV5055Z4QDBZR	DRV5056A4QDBZR	DRV5056Z3QDBZR	

## Qualification Report

Approve Date 18-December-2023

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: DRV5055A1QDBZR	Qual Device: DRV5055A2QDBZR	Qual Device: DRV5055A3QDBZR	Qual Device: DRV5055A4QDBZR	QBS Reference: TLV62568DBVR	QBS Reference: TLV62569DBVR	QBS Reference: DRV5013ADEDBZRQ1	QBS Reference: DRV5013ADQDBZRQ1	QBS Reference: TL431BCQDBZRQ1	QBS Reference: PTMAG5253BA3QDBZR
HAST	A2	Biased HAST	130C	96 Hours	-	-	-	-	3/231/0	3/231/0	-	-	-	-
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	-	3/231/0	3/231/0	-	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	-	-	3/231/0	3/231/0	3/231/0	-
TC	A4	Temperature Cycle	-55C/150C	1000 Cycles	-	-	-	-	-	-	-	3/231/0	-	-
TC	A4	Temperature Cycle	-55C/150C	1500 Cycles	-	-	-	-	-	-	3/231/0	-	-	-
TC	A4	Temperature Cycle	-65/150C	500 Cycles	-	-	-	-	3/231/0	3/231/0	-	-	-	1/77/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-	3/231/0	3/231/0	-	-	3/231/0	1/77/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	-	3/231/0	-	3/135/0	3/231/0	-
HTSL	A6	High Temperature Storage Life	150C	2000 Hours	-	-	-	-	-	-	3/135/0	-	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	-	3/231/0	-	-	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	-	3/231/0	-	-	-	-
HTOL	B1	Life Test	150C	1000 Hours	-	-	-	-	-	-	1/77/0	-	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	-	-	3/231/0	-	-	1/77/0	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	-	3/3000/0	3/2400/0	-	-	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	-	-	1/15/0	1/15/0	-	-

Type	#	Test Name	Condition	Duration	Qual Device: DRV5055A1QDBZR	Qual Device: DRV5055A2QDBZR	Qual Device: DRV5055A3QDBZR	Qual Device: DRV5055A4QDBZR	QBS Reference: TLV62568DBVR	QBS Reference: TLV62569DBVR	QBS Reference: DRV5013ADEDBZRQ1	QBS Reference: DRV5013ADQDBZRQ1	QBS Reference: TL43180QDBZRQ1	QBS Reference: PTMAG5253BA3QDBZR
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	-	-	1/15/0	1/15/0	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	-	-	-	-	-	-	-	-	1/22/0
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	-	-	-	3/30/0	3/30/0	3/30/0	-
ESD	E2	ESD CDM	-	1500 Volts	-	-	-	-	1/3/0	3/9/0	-	-	-	-
ESD	E2	ESD CDM	-	250 Volts	-	-	1/3/0	-	-	-	-	-	-	-
ESD	E2	ESD CDM	-	500 Volts	-	-	-	-	-	-	1/3/0	1/3/0	-	-
ESD	E2	ESD HBM	-	1000 Volts	-	-	1/3/0	-	-	-	-	-	-	-
ESD	E2	ESD HBM	-	2000 Volts	-	-	1/3/0	-	-	3/9/0	1/3/0	1/3/0	-	-
ESD	E2	ESD HBM	-	3500 Volts	-	-	-	-	1/3/0	3/9/0	-	-	-	-
LU	E4	Latch-Up	Per JESD78	-	-	-	1/3/0	-	1/6/0	3/9/0	1/6/0	1/6/0	-	-
CHAR	E5	Electrical Characterization	Min, Typ, Max Temp	-	-	-	1/30/0	-	1/30/0	3/90/0	-	-	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	-	1/30/0	-	1/30/0	3/90/0	-	-	-	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	-	-	-	-	2/60/0	3/90/0	3/90/0	-
FTY	E6	Final Test Yield	-	-	1/1/0	1/1/0	-	1/1/0	-	-	-	-	1/1/0	-

#### QBS: Qual By Similarity

Qual Device DRV5055A1QDBZR is qualified at MSL1 260C

Qual Device DRV5055A2QDBZR is qualified at MSL1 260C

Qual Device DRV5055A3QDBZR is qualified at MSL1 260C

Qual Device DRV5055A4QDBZR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

### IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale ([www.ti.com/legal/termsofsale.html](http://www.ti.com/legal/termsofsale.html)) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.